4870-4875

Sn60/Pb40 No-Clean Solder Wires

4870–4875 electronic grade solder wires use a tin-to-lead alloy ratio, with a no-clean, synthetically refined, splatter-proof resin flux core. They melt at a higher and wider temperature range than 63/37 solder. They create robust and reliable joints that are highly resistant to whisker formation.

These leaded solders achieve a consistent solder and flux percentage thanks to our state-ofthe-art extrusion wire-drawing machine, which continuously monitors the wire to prevent voids and ensure consistency, providing a top-grade solder wire

Features & Benefits

Alloy exceeds J-STD-006C and meets ASTM B 32 purity requirements

Flux meets J-STD-004B

Particle size Type 3

Excellent 12 mil fine pitch printing capability

Long operational life—non-slumping

Good wettability

Halogen-free

Available Packaging

Part #	Packaging	Gauge	Diameter	Net Wt.
4870-18G	Pocket Pack	21	0.032"	18 g
4875-227G	Spool	21	0.032"	227 g

Storage and Handling

Store between 18 and 25 ˚C in a dry area, away from sunlight (see SDS).

This product can expose you to chemicals including lead, which is known to the State of California to cause cancer and birth defects or other reproductive harm. For more information go to **www.P65Warnings.ca.gov**.

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Properties

Flux Classification	REL0	J-STD-004B, MIL-F-14256F
Flux Type	Resin	J-STD-004B
Flux Activity	Low	J-STD-004B
Copper Mirror	Pass	IPC-TM-650 2.3.32
Corrosion Test	Pass	IPC-TM-650 2.6.15
Flux Residue Dryness	Pass	IPC-TM-650 2.4.47
Surface Insulation Resistance (SIR)	2.3 x 10^{11} Ω	IPC-TM-650 2.6.3.7
Electromigration (ECM)	Pass	Bellcore GR-78-CORE 13.1.4
Acid Number (mgKOH/g sample)	190–210	IPC-TM-650 2.3.13
Halides (by weight)	<0.05%	IPC-TM-650 2.3.35
Silver Chromate (Cl^- + Br^-)	Pass	—
Softening Point of Flux Residue	24 °C	—
Solder Spread	130 mm^2	—
Splitting of Flux, cored wire solder	0.30 %	—
Post Reflow Flux Residue	55 %	—
Bellcore (Telecordia)	6.1 x 10^{11} Ω	—
Shelf Life	10 y	—